

WHAT IS CLAIMED IS:

1 1. An information handing system comprising:
2 plural components operable to process information;
3 a motherboard interfacing the plural components to communicate the
4 information;
5 a socket frame coupled to the motherboard;
6 a socket disposed within the socket frame and coupled to the motherboard, the
7 socket having plural connectors in electrical communication with the
8 motherboard;
9 a processor coupled to the socket, the processor having plural connectors
10 aligned to couple with the socket connectors;
11 a load plate coupled to the socket frame and having a closed position and an
12 opened position over the processor, the load plate closed position
13 compressing the processor connectors into the socket connectors; and
14 a processor extraction device disposed proximate the load plate and operable
15 to extract the processor from the socket upon movement of the load
16 plate from a closed to an open position.

1 2. The information handling system of Claim 1 wherein the processor
2 comprises a central processing unit.

1 3. The information handling system of Claim 2 wherein the central
2 processor unit connectors and socket connectors comprise land grid array connectors.

1 4. The information handling system of Claim 1 wherein the processor
2 extraction device comprises adhesive disposed between the load plate and the
3 processor, the adhesive coupling the load plate to the processor during movement of
4 the load plate from the closed to the open position.

1 5. The information handling system of Claim 1 wherein the processor
2 extraction device comprises a spring disposed between the processor and the

3 motherboard, the spring biasing the processor out of the socket and against the load
4 plate.

1 6. The information handling system of Claim 5 wherein the processor
2 extraction device further comprises plural springs disposed between the processor and
3 the motherboard to provide a uniform extraction forces to the processor.

1 7. The information handling system of Claim 5 wherein the processor
2 extraction device further comprises adhesive disposed between the load plate and the
3 processor, the adhesive coupling the processor to the load plate during transition from
4 the closed position to the open position.

1 8. A method for extracting a processor from a socket, the method
2 comprising:
3 moving a load plate from a closed position that compresses the processor into
4 the socket to an open position;
5 activating an extraction device by movement of the load plate from the closed
6 position to the open position; and
7 extracting the processor from the socket with the activated extraction device.

1 9. The method of Claim 8 wherein extracting the processor from the
2 socket further comprises:
3 coupling the processor to the load plate with an adhesive; and
4 lifting the processor from the socket by movement of the load plate away from
5 the socket.

1 10. The method of Claim 8 wherein extracting the processor from the
2 socket further comprises:
3 decompressing a spring disposed under the processor by moving the load plate
4 from the closed to the open position; and
5 pushing the processor from socket by decompression of the spring.

1 11. The method of Claim 10 wherein moving the load plate decompresses
2 plural springs disposed around a heat spreader of the processor to apply a
3 substantially even pushing force for extracting the processor from the socket.

1 12. The method of Claim 8 wherein extracting the processor from the
2 socket further comprises:
3 initiating extraction of the processor from the socket with springs aligned to
4 push the processor with the load plate during movement of the load
5 plate from the closed to the open position; and
6 adhering the processor to the load plate to lift the processor from the socket by
7 translation of lifting motion applied to the load plate.

1 13. The method of Claim 8 wherein the processor and socket couple by
2 land grid array connectors.

1 14. A system for extracting a processor from a processor socket, the
2 system comprising:
3 a socket frame operable to couple to a circuit board proximate a processor
4 socket;
5 a load plate coupled to the socket frame and operable to move between a
6 closed position that compresses the processor and an open position that
7 exposes the processor; and
8 a processor extraction device operable to automatically extract the processor
9 from the socket at movement from the closed position to the open
10 position.

1 15. The system of Claim 14 wherein the processor extraction device
2 comprises a spring engaged with the processor to compress with the load plate in the
3 closed position and to apply an extraction force to the processor if the load plate
4 transitions to the opened position.

1 16. The system of Claim 14 wherein the processor extraction device
2 comprises plural springs operable to engage with the processor to compress with the
3 load plate in the closed position and to apply an extraction force to the processor if the
4 load plate transitions to the opened position.

1 17. The system of Claim 14 wherein the processor extraction device
2 comprises adhesive operable to couple the processor to the load plate.

1 18. The system of Claim 17 further comprising one or more springs
2 aligned to bias the processor out of the socket.

1 19. The system of Claim 14 further comprising:
2 a land grid array socket disposed in the socket frame; and
3 a land grid array processor coupled to the socket.

1 20. The system of Claim 19 wherein the processor comprises a central
2 processor unit.